503410552 07/28/2015

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3457187

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Tung Hsiao	07/23/2015
Keng-Jen Lin	07/23/2015
Yu-Ren Wang	07/23/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14810500

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2547USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	07/28/2015

Total Attachments: 6

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PATENT REEL: 036189 FRAME: 0032

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

MANUFACTURING METHOD OF SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	filed on	, or	
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be made	by me.	***********
I believe that I am the original invent application.	or or an original joint inventor of	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this de isonment of not more than five (5	claration is punishable i) years, or both.	
In consideration of the payment by	UNITED MICROELECTRO CORP.	NICS having a postal add	ress of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hs	in-Chu City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1. nd valuable consideration.	00), the receipt of which is he	reby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements v tion and, in and to, all Letters Pa r any continuations, continuation-	which are disclosed in the tent to be obtained for said in part, divisions, renewals.	EE
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrat n this assignment;	nce has been or will be made	or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be erence. litigation proceeding	ts
representatives any and all papers, is maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have he	dication, said invention and said lecessary or desirable to carry out	Letters Patent and said the proposes thereof.	f signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for each ad	naming the entire ditional inventor.	

Page 1 of 6

Docket No NAUP2547USA

LEGAL NA	ME OF INVENTOR(AS	rs)	
Inventor:	Yu-Tung Hsiao	Date:JUL_ 2 3 2015	
Signature:	Tu-Tung	Ö	

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NPO#NAU-P2547-USA:0

CUST#UMCD-2015-0301

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☑ The attached application, or				
☐ United States application number		filed	on	, or
☐ PCT international application	□ PCT international application number		ed on	
The above-identified application was	made or authoriz	zed to be made by me.		
I believe that I am the original inventapplication.	or or an original jo	oint inventor of a claime	ed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement i isonment of not m	made in this declaration nore than five (5) years	n is punishable , or both.	
In consideration of the payment by	UNITED MICR	OELECTRONICS	having a postal ac	dress of
No.3, Li-Hsin Road 2, Science	-Based Indust	rial Park, Hsin-Chu	_ ப City 300, Taiwa	n, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of C ad valuable consid	One Dollar (\$ 1.00), the deration.	receipt of which is h	ereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, an	nd to any and all i tion and, in and to rany continuation	mprovements which ar o, all Letters Patent to t s, continuation-in-part.	e disclosed in the be obtained for said divisions, renewals.	
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreemer n this assignment;	nt or encumbrance has	been or will be mad	e or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exer	ition and said Lett stify as to the san	ters Patent and legal ed ne in any interference,	quivalents as may be litigation proceeding	Э
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said inve cessary or desira	ntion and said Letters ble to carry out the pro	Patent and said poses thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany this				

Page 3 of 6

NPO#NAU-P2547-USA:0 CUST#UMCD-2015-0301

Docket No NAUP2547USA

LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Keng-Jen Lin	Date:	JUL 23 2015	
Signature:	Court Jen Xi	Status		

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NPO#NAU-P2547-USA:0 CUST#UMCD-2015-0301

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: MANUFACTURING METHOD OF SEMICONDUCTOR STRUCTURE

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☑ The attached application, or				
☐ United States application number			n	, or
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The above-identified application was	s made or authorized to	be made by me.		
I believe that I am the original invent application.	or or an original joint inv	entor of a claime	d invention in t	he
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made isonment of not more th	in this declaration an five (5) years,	is punishable or both.	
In consideration of the payment by	UNITED MICROEL CORP.	ECTRONICS	having a post	tal address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial F	ark, Hsin-Chu	_ City 300, Ta	alwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			eceipt of which	n is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improv ition and, in and to, all L r any continuations, con	ements which are etters Patent to be tinuation-in-part, o	disclosed in the obtained for standard divisions, renew	he said wals,
I hereby covenant that no assignment entered into which would conflict with		ncumbrance has	been or will be	made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Pa estify as to the same in a	atent and legal eq any interference, li	uivalents as m itigation procee	ay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said invention a ecessary or desirable to	and said Letters F carry out the prop	Patent and said poses thereof.	l Date of signing
Note: An application data sheet (PT0 inventive entity, must accompany thi				

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NPO#NAU-P2547-USA:0 CUST#UMCD-2015-0301

Docket No NAUP2547USA

LEGAL NA	ME OF INVENTOR(A	(SSIGNOR)		•	
Inventor:	Yu-Ren Wang		Date:	JUL 23 2015	
Signature:	Yu-Ren	Wang	***************************************		

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NPO#NAU-P2547-USA:0 CUST#UMCD-2015-0301

RECORDED: 07/28/2015

F#NPO-P0002E-US1201 DSC0-104U007699

PATENT REEL: 036189 FRAME: 0038